

Approval Sheet Records

CUSTOMER	Aselsan	CUST P/N	TSDR437P5B31			
DESCRIPTION	SMD Band Pass Filter	Temstron P/N	TSDR437P5B31			
Item	Date	Page	Revised	Version	Sample App No	Remark
1	2018-02-10	/	Spec finish	REV.A1	PD20180027	

SPECIFICATION

Part No.: TSDR437P5B31

Customer: Aselsan

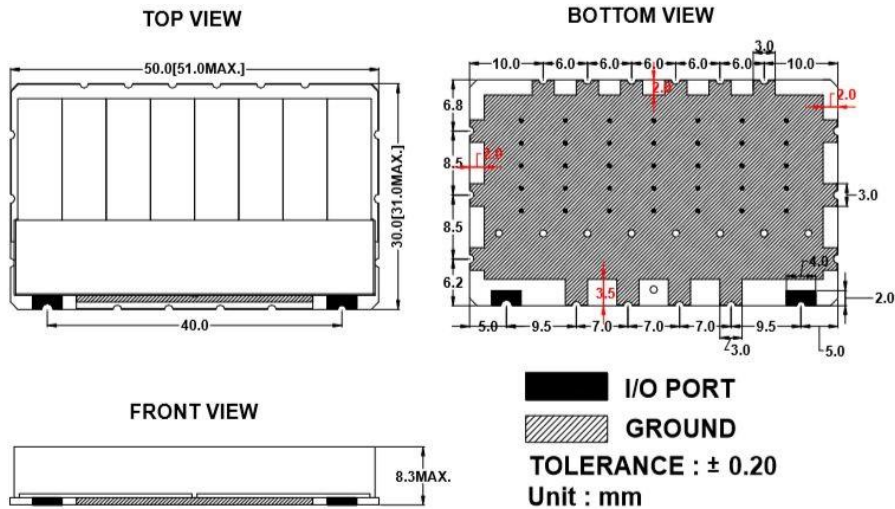
Date: 2018.07.31

Written by	Checked by	Approval
FL Lai	MY Chen	CK Chang

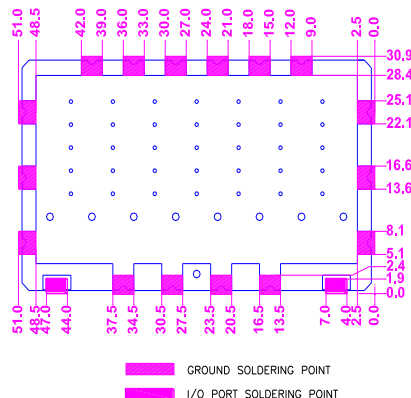
ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT	
1	Center freq	437.5	MHz
2	Bandwidth [1dB BW]	31.0 [422.0~453.0]	min MHz
	Bandwidth [3dB BW]	75.0	maz MHz
3	Insertion Loss in BW	3.0	dB max.
4	Ripple in BW		dB max.
5	Return Loss in BW		dB min.
6	V S W R in BW	1.5	max.
7	Attenuation (Absolute Value)	40 dB min. DC-400.0MHz 40 dB min. @ 475-875 MHz	MHz
8	Group Delay Variation	1 any 2MHz	ns max
9	Input Power	3.0	W
10	In/Out Impedance	50Ω	Ω
11	Operation Temperature Range	-40°C to +85°C	°C

MECHANICAL SPECIFICATIONS



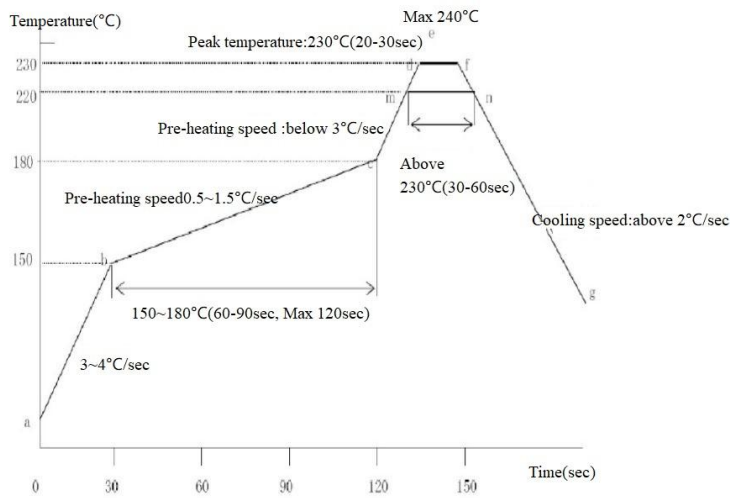
RECOMMENDED PC BOARD PATTERN



Temstron PN	TDRF2362B225	Q'TY	10PCS
Lot No	20180143-2	Date	2018.07.31

REFLOW SOLDERING STANDARD CONDITION

1. Please ensure a good ground(area between GROUND and I/O PORT) when you use the PCB packaging product. In order to ensure the good ground, please repair welding for the lateral pin after welding the bottom area.
2. SMT is recommended to you for using this product. The graph above shows recommendatory reflow profile. Since the different performance between the substrate and the reflow, please refer to the both devices to confirm the actual temperature profile.
3. Soldering can be only for PCB packaging product, it is forbidden for ceramic dielectric product.



PERFORMANCE

